

Emulation Solutions

An Embedded Systems Solutions Company
www.adapters.com

Surface Mountable Emulator Adapters

PolyPod line

These adapters, called BASEs, surface mount directly to the target board in place of the integrated circuit under test or being emulated.

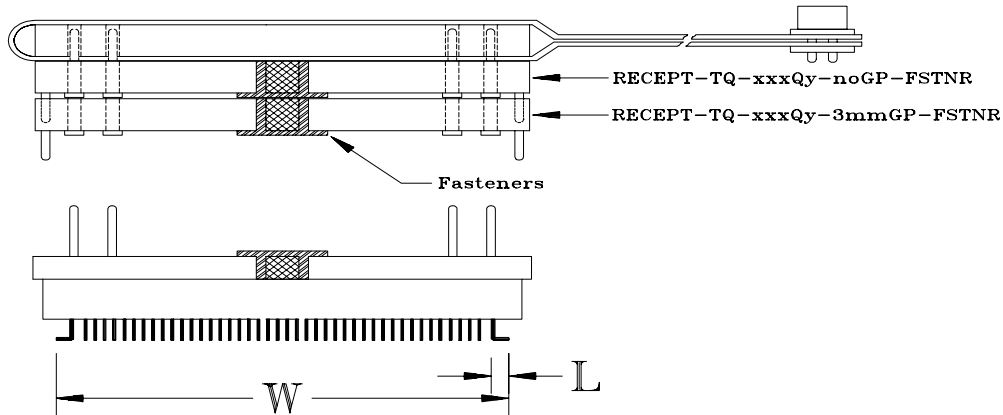
The optional RECEPTACLES are used to provide a solid interface between the BASEs and a user defined interface board or flex-cable circuit.

Fasteners are built into the BASE and the RECEPTACLE, allowing the user to create a very sturdy test setup by bolting the various assemblies together.

Several major emulator makers have designed their emulator interface cables to plug directly onto these emulator bases.

Application:

BASE-TQ-xxxQy-SMT plus RECEP-TQ-xxxQy-noGP-FSTNR plus PCB or FLEX cable interfaces to test instrument.



Part numbering system: BASE-TQ-208Q5-SMT

BASE-TQ	208	Q	5	SMT
Product code (emulator version)	Pin count (208)	Package Code (PQFP)	Pitch (0.5 mm)	Function code (surface mount)

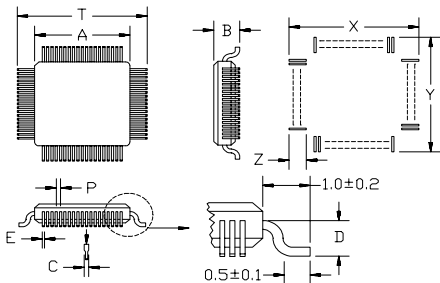
Notes for the table below:

* Denotes a depopulated pin count.

Pin count	Adapter and IC dimensions					PCB layout for adapter (see note below!!!)		
	Pitch (P)	Body size (A)	Tip-to-Tip (W)	L	C	X	Y	Z
32	0.80	7.0 x 7.0	9.2 x 9.2	1.25	0.5	10.2	10.2	2.0
44	0.80	10.0 x 10.0	12.0 x 12.0	1.325	0.5	13.0	13.0	2.0
44	1.00	14.0 x 14.0	16.4 x 16.4	2.325	0.6	17.4	17.4	3.0
48	0.80	10.0 x 10.0	12.0 x 12.0	0.925	0.5	13.0	13.0	1.8
52	0.65	10.0 x 10.0	12.0 x 12.0	1.425	0.35	13.0	13.0	2.2
56	0.65	10.0 x 10.0	12.5 x 12.5	1.35	0.35	13.5	13.5	2.2
64	0.80	14.0 x 14.0	16.0 x 16.0	1.325	0.5	17.0	17.0	2.1
64	0.50	10.0 x 10.0	12.0 x 12.0	1.505	.25	13.0	13.0	2.3
64	0.65	12.0 x 12.0	14.0 x 14.0	1.45	0.35	15.0	15.0	2.2
64	1.00	14.0 x 14.0	16.0 x 22.0	1.125	0.6	17.0	23.0	2.0
72	0.50	10.0 x 10.0	12.0 x 12.0	1.0	0.25	13.0	13.0	1.9
80	0.50	12.0 x 12.0	14.0 x 14.0	1.505	0.25	15.0	15.0	2.3
80	0.65	14.0 x 14.0	16.0 x 16.0	1.15	0.35	17.0	17.0	2.0
80	1.00	14.0 x 14.0	16.0 x 22.0	1.325	0.6	17.0	23.0	1.9
100	0.80	22.0 x 22.0	24.0 x 24.0	1.725	0.5	25.0	25.0	2.5
100	0.50	14.0 x 14.0	16.5 x 16.5	1.125	0.25	17.5	17.5	2.15
100	0.65	14.0 x 14.0	16.0 x 22.5	1.125	0.35	17.0	23.5	2.0
112	0.65	20.0 x 20.0	22.0 x 22.0	1.0	0.35	23.0	23.0	1.9
120	0.50	16.0 x 16.0	18.0 x 18.0	1.005	0.25	19.0	19.0	1.9
120/128*	0.80	28.0 x 28.0	31.4 x 31.4	2.625	0.5	32.4	32.4	3.4
128	0.80	28.0 x 28.0	31.4 x 31.4	2.625	0.5	32.4	32.4	3.4
128	0.50	14.0 x 14.0	16.0 x 22.0	1.005	0.25	17.0	23.0	1.9
132	0.635	24.2 x 24.2	27.5 x 27.5	1.125	0.35	28.5	28.5	2.15
120/144*	0.50	20.0 x 20.0	22.0 x 22.0	1.125	0.25	23.0	23.0	2.15
144	0.50	20.0 x 20.0	22.0 x 22.0	1.125	0.25	23.0	23.0	2.15
144/160*	0.65	28.0 x 28.0	30.0 x 30.0	1.65	0.35	31.0	31.0	2.5
160	0.65	28.0 x 28.0	30.0 x 30.0	1.65	0.35	31.0	31.0	2.5
176	0.50	24.2 x 24.2	26.0 x 26.0	1.125	0.25	27.0	27.0	1.9
184	0.65	32.0 x 32.0	34.0 x 34.0	1.7	0.35	35.0	35.0	2.5
208	0.50	28.0 x 28.0	30.0 x 30.0	1.125	0.25	31.0	31.0	2.15
256	0.50	27.2 x 39.2	29.2 x 41.2	1.105	0.25	31.0	31.0	2.15

***NOTE:** The pad layout recommendations are for the adapters only. If users intend to solder an actual package on the target, they must consider the physical footprint of that package. Some packages have much larger footprints, where footprint is defined as “Tip to Tip dimension minus the package size”, in mathematical terms:

FP = T - A as illustrated on the IC package diagram below:



The American (JEDEC) and Japanese (EIAJ) standardization committees defined the following footprints:

2.0 mm, 2.6 mm, 3.2 mm, and 3.9 mm

In other words, a package with a 3.9 mm footprint and a body size of 28 mm will have a “tip to tip” dimension (T) of 31.9 mm. The recommended X/Y dimension for that package would be a minimum of 33.9 mm.

The recommended X/Y dimensions in our table for that size is only 31.0 mm.

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